

# RHyNO™ HPM

RHyNO™ HYBRID PROTOTYPING MODULE

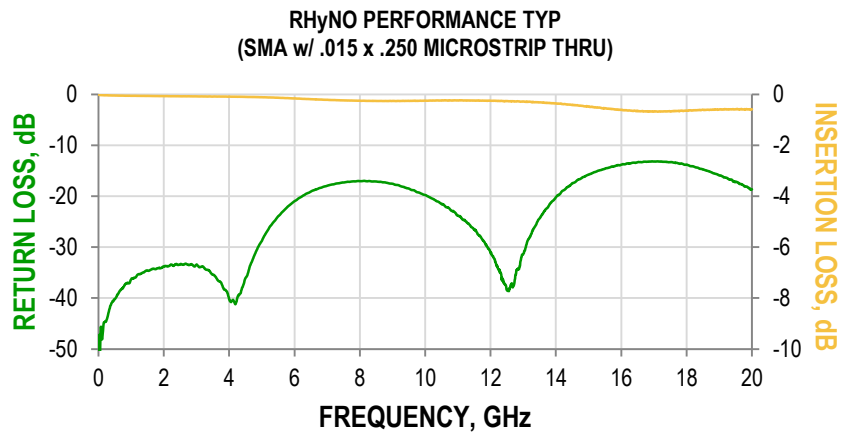
REV 1.2.0



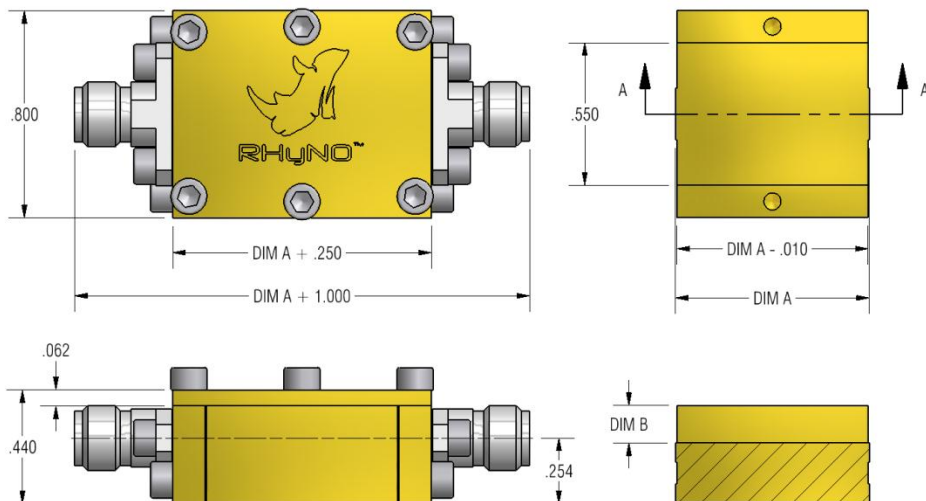
RHyNO™ is a high performance housing used for hybrid prototyping. These modules are designed to provide engineers the means for quick prototyping and optimizing of their hybrid circuit. In addition, it can also be extended to evaluate other components such as surface mount and planar devices. The RHyNO™ will enable quick testing, easy circuit swapping, and trouble-free circuit assembly.

## SPECIFICATIONS

SPECIFICATION	VALUE
IMPEDANCE	50 Ω
MAX FREQ	20 GHz
VSWR TYP	1.12 @ 5GHz 1.35 @ 8GHz 1.60 @ 18GHz
ILOSS TYP	0.10 dB @ 5GHz 0.25 dB @ 5GHz 0.70 dB @ 18GHz
MATERIAL	BRASS
FINISH	NICKEL/GOLD



## MECHANICAL OUTLINE



### BASE

DIM A = BASE LENGTH

DIM B = .143 ± .005 (.010 MS THK)

DIM B = .148 ± .005 (.015 MS THK)

DIM B = .153 ± .005 (.020 MS THK)

### CONNECTORS

SMA

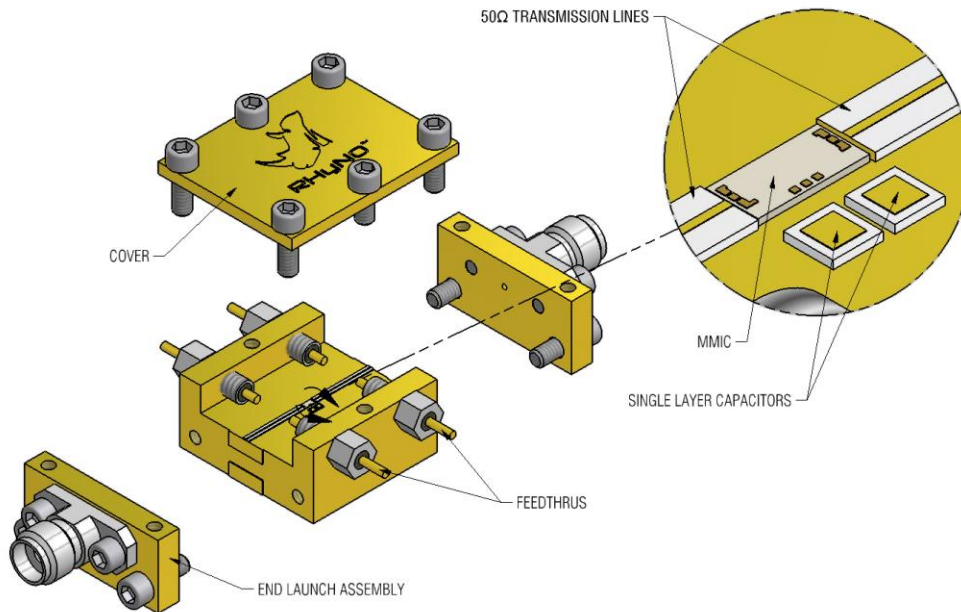
2.92 mm

\* Cover will not include RHyNO™ logo

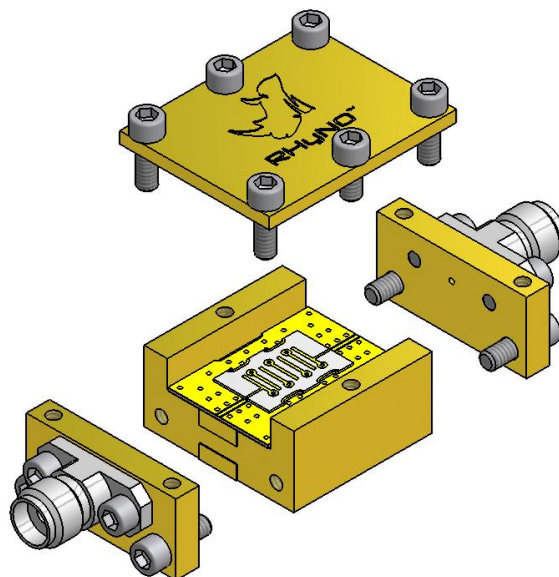
† Dimensions with SMA(F) connectors

## TYPICAL APPLICATIONS

The below illustrates how the RHyNO™ can be assembled and used in a typical hybrid circuit design. Epoxy is the recommended attachment method. The illustration shows the RHyNO™ with customized feedthrus (not included). Please contact sales for customization options.



The RHyNO™ can also be customized to measure surface mount devices. Below shows an example of a filter mounted on a grounded-coplanar waveguide carrier board.



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## ORDERING INFO

### STANDARD MODULE

The RHyNO™ module comes as a kit with the launcher assembly, base, cover, and four 100 mil long microstrip. Cover will not include the RHyNO™ logo. For all parts, please contact [sales@electro-photonics.com](mailto:sales@electro-photonics.com) for your custom needs.

**H P M - X X X X - X X X X - X X 1 0 0 - X X X X - B N G**  
 ①                      ②                      ③                      ④      ⑤                      ⑥                      ⑦

### BASE ONLY

**H P B - X X - X X X X - B N G**  
 ①                      ④                      ⑥                      ⑦

### COVER ONLY

**H P C - X X X X - B N G**  
 ①                      ⑥                      ⑦

① PART	② LAUNCH	③	④ MS THICKNESS	⑤ MS LENGTH	⑥ BASE LENGTH	⑦ MATERIAL/FINISH
HPM = MODULE HPB = BASE HPC = COVER	L01F = SMA (F) L01M = SMA (M)  L02F = 2.92 mm (F) L02M = 2.92 mm (M)		10 = 10 MIL 15 = 15 MIL 20 = 20 MIL	100 = 100 MIL	XXXX = MIL (PLEASE SPECIFY)  MIN LENGTH = 0225 MIL (ALLOW ROOM FOR MICROSTRIP IF NECESSARY)	BNG = BRASS/NICKEL/GOLD